

## 具有漏极开路输出的 SN74LVC1G07 单路缓冲器/驱动器

### 1 特性

- 采用具有 0.5mm 间距的超小型 0.64mm<sup>2</sup> 封装 (DPW)
- 支持 5V V<sub>CC</sub> 运行
- 输入与开漏输出支持最高 5.5V 的电压
- 可进行上行或下行转换
- 电压为 3.3V 时, t<sub>pd</sub> 最大值为 4.2ns
- 低功耗, 10μA 最大 I<sub>CC</sub>
- 电压为 3.3V 时, 输出驱动为 ±24mA
- I<sub>off</sub> 支持带电插入、局部关断模式和后驱动保护
- 闩锁性能超过 100mA, 符合 {13}JESD 78 II 类规范
- ESD 保护性能超过 JESD 22 规范要求
  - 2000V 人体放电模型 (A114-A)
  - 200V 机器模型 (A115-A)
  - 1000V 充电器件模型 (C101)

### 2 应用

- AV 接收器
- 蓝光播放器与家庭影院
- DVD 录像机和播放器
- 台式机或笔记本电脑
- 数字音频广播或互联网广播播放器
- 数码摄像机 (DVC)
- 嵌入式计算机
- GPS: 个人导航设备
- 移动因特网设备
- 网络投影仪前端
- 便携式媒体播放器
- 专业音频混合器
- 烟雾探测器
- 固态硬盘 (SSD): 企业
- 高清 (HDTV)
- 平板电脑: 企业
- 音频接口盒: 便携式
- DLP 正投影系统
- DVR 和 DVS
- 数码相框 (DPF)
- 数码相机

### 3 说明

此单路缓冲器/驱动器专为 1.65V 至 5.5V V<sub>CC</sub> 工作电压而设计。

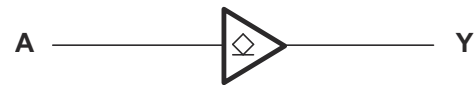
SN74LVC1G07 器件的输出为漏极开路, 可连接其它开漏输出, 从而实现低电平有效的连线 OR 或高电平有效的连线 AND 功能。最大灌电流为 32mA。

SN74LVC1G07 采用多种封装, 包括外形尺寸为 0.8mm × 0.8mm 的超小型 DPW 封装。

#### 器件信息

| 器件名称           | 封装 <sup>(1)</sup> | 封装尺寸            |
|----------------|-------------------|-----------------|
| SN74LVC1G07DBV | SOT-23 (5)        | 2.9mm × 1.6mm   |
| SN74LVC1G07DCK | SC70 (5)          | 2.0mm × 1.25mm  |
| SN74LVC1G07DPW | X2SON (5)         | 0.8mm × 0.8mm   |
| SN74LVC1G07DRY | SON (6)           | 1.45mm × 1.0mm  |
| SN74LVC1G07DSF | SON (6)           | 1.0mm × 1.0mm   |
| SN74LVC1G07DRL | SOT (5)           | 1.6mm × 1.2mm   |
| SN74LVC1G07YZP | DSBGA (6)         | 1.38mm × 0.88mm |
| SN74LVC1G07YZV | DSBGA (4)         | 0.88mm × 0.88mm |

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。



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## 4 Revision History

注：以前版本的页码可能与当前版本的页码不同

### Changes from Revision AD (May 2016) to Revision AE (September 2020) Page

- 更新了整个文档的表、图和交叉参考的编号格式。..... 1

### Changes from Revision AC (April 2014) to Revision AD (April 2016) Page

- 将器件信息表中 DPW 封装的 4 引脚更改为 5 引脚..... 1
- 向器件信息表添加了 DRL、YZP 和 YZV 封装信息和封装尺寸..... 1
- Moved "T<sub>stg</sub> Storage temperature range" from ESD Ratings table to Absolute Maximum Ratings table..... 5
- Added "T<sub>j</sub> Junction temperature range" to Absolute Maximum ratings table..... 5
- Split "T<sub>A</sub> Operating free-air temperature" into package specific temperature ranges in Recommended Operating Conditions table..... 6
- Changed "H" to "Z" in Output Y column of Function Table ..... 10

### Changes from Revision AB (March 2014) to Revision AC (April 2014) Page

- Updated Handling Ratings table. .... 5
- Added Thermal Information table. .... 6
- Added Typical Characteristics. .... 8
- Added Application and Implementation section. .... 11
- Added Power Supply Recommendations section. .... 12

### Changes from Revision AA (July 2013) to Revision AB (February 2014) Page

- 更新了“特性”..... 1
- 添加了“应用”..... 1
- 添加了“器件信息”表..... 1
- Added Pin Functions table. .... 4
- Moved T<sub>stg</sub> to Handling Ratings table..... 5

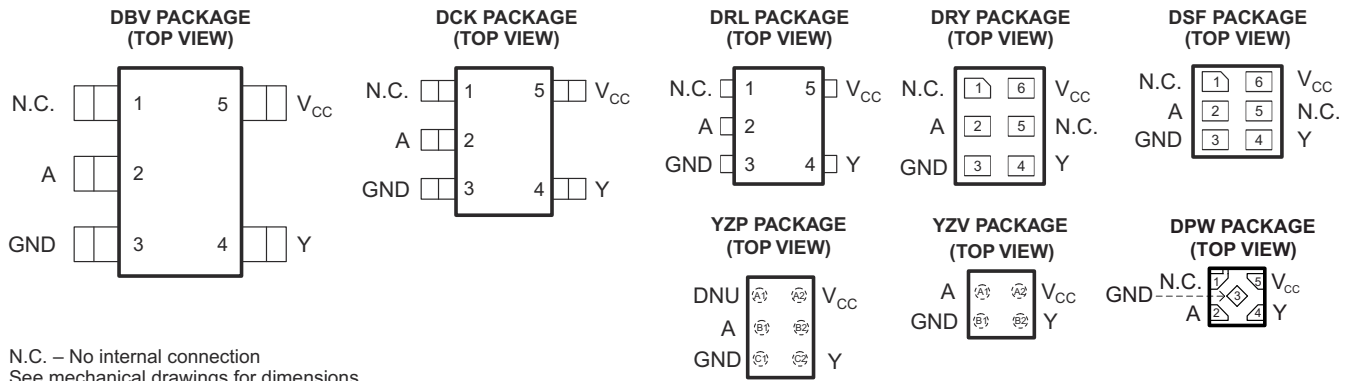
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**Changes from Revision Z (November 2012) to Revision AA (July 2013)**

**Page**

- Extended maximum temperature operating range from 85°C to 125°C..... **6**
-

## 5 Pin Configuration and Functions



### Pin Functions

| NAME            | PIN           |          |     |        |     | DESCRIPTION   |
|-----------------|---------------|----------|-----|--------|-----|---------------|
|                 | DBV, DCK, DRL | DRY, DSF | DPW | YZP    | YZV |               |
| NC              | 1             | 1, 5     | 1   | A1, B2 | -   | Not connected |
| A               | 2             | 2        | 2   | B1     | A1  | Input         |
| GND             | 3             | 3        | 3   | C1     | B1  | Ground        |
| Y               | 4             | 4        | 4   | C2     | B2  | Output        |
| V <sub>CC</sub> | 5             | 6        | 5   | A2     | A2  | Power pin     |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|                  |   | MIN   | MAX  | UNIT |
|------------------|---|-------|------|------|
| V <sub>CC</sub>  | Supply voltage range  | - 0.5 | 6.5  | V    |
| V <sub>I</sub>   | Input voltage range <sup>(2)</sup>  | - 0.5 | 6.5  | V    |
| V <sub>O</sub>   | Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup> | - 0.5 | 6.5  | V    |
| V <sub>O</sub>   | Voltage range applied to any output in the high or low state <sup>(2) (3)</sup>             | - 0.5 | 6.5  | V    |
| I <sub>IK</sub>  | Input clamp current   |       | - 50 | mA   |
| I <sub>OK</sub>  | Output clamp current  |       | - 50 | mA   |
| I <sub>O</sub>   | Continuous output current   |       | ±50  | mA   |
|                  | Continuous current through V <sub>CC</sub> or GND   |       | ±100 | mA   |
| T <sub>stg</sub> | Storage temperature range   | - 65  | 150  | °C   |
| T <sub>J</sub>   | Junction temperature range  |       | 150  | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the *Recommended Operating Conditions* table.

### 6.2 ESD Ratings

|                    |                         | MIN  | MAX | UNIT |   |
|--------------------|-------------------------|--|-----|------|---|
| V <sub>(ESD)</sub> | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>              | 0   | 2000 | V |
|                    |                         | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup> | 0   | 1000 |   |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|                         |                                    |   | MIN                    | MAX                    | UNIT |
|-------------------------|------------------------------------|---|------------------------|------------------------|------|
| V <sub>CC</sub>         | Supply voltage                     | Operating                                       | 1.65                   | 5.5                    | V    |
|                         |                                    | Data retention only                             | 1.5                    |                        |      |
| V <sub>IH</sub>         | High-level input voltage           | V <sub>CC</sub> = 1.65 V to 1.95 V              | 0.65 × V <sub>CC</sub> |                        | V    |
|                         |                                    | V <sub>CC</sub> = 2.3 V to 2.7 V                | 1.7                    |                        |      |
|                         |                                    | V <sub>CC</sub> = 3 V to 3.6 V                  | 2                      |                        |      |
|                         |                                    | V <sub>CC</sub> = 4.5 V to 5.5 V                | 0.7 × V <sub>CC</sub>  |                        |      |
| V <sub>IL</sub>         | Low-level input voltage            | V <sub>CC</sub> = 1.65 V to 1.95 V              |                        | 0.35 × V <sub>CC</sub> | V    |
|                         |                                    | V <sub>CC</sub> = 2.3 V to 2.7 V                |                        | 0.7                    |      |
|                         |                                    | V <sub>CC</sub> = 3 V to 3.6 V                  |                        | 0.8                    |      |
|                         |                                    | V <sub>CC</sub> = 4.5 V to 5.5 V                |                        | 0.3 × V <sub>CC</sub>  |      |
| V <sub>I</sub>          | Input voltage                      |   | 0                      | 5.5                    | V    |
| V <sub>O</sub>          | Output voltage                     |   | 0                      | 5.5                    | V    |
| I <sub>OL</sub>         | Low-level output current           | V <sub>CC</sub> = 1.65 V                        |                        | 4                      | mA   |
|                         |                                    | V <sub>CC</sub> = 2.3 V                         |                        | 8                      |      |
|                         |                                    | V <sub>CC</sub> = 3 V                           |                        | 16                     |      |
|                         |                                    |   |                        | 24                     |      |
| V <sub>CC</sub> = 4.5 V |                                    | 32  |                        |                        |      |
| Δt/Δv                   | Input transition rise or fall rate | V <sub>CC</sub> = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V |                        | 20                     | ns/V |
|                         |                                    | V <sub>CC</sub> = 3.3 V ± 0.3 V                 |                        | 10                     |      |
|                         |                                    | V <sub>CC</sub> = 5 V ± 0.5 V                   |                        | 5                      |      |
| T <sub>A</sub>          | Operating free-air temperature     | DSBGA package                                   | - 40                   | 85                     | °C   |
|                         |                                    | All other packages                              | - 40                   | 125                    |      |

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> | SN74LVC1G07                                  |        |        |        |        |        | UNIT |      |
|-------------------------------|--|--------|--------|--------|--------|--------|------|------|
|                               | DBV  | DCK    | DRL    | DRY    | YZP    | DPW    |      |      |
|                               | 5 PINS                                       | 5 PINS | 5 PINS | 6 PINS | 5 PINS | 4 PINS |      |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 229    | 278    | 243    | 439    | 130    | 340  | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 164    | 93     | 78     | 277    | 54     | 215  |      |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 62     | 65     | 78     | 271    | 51     | 294  |      |
| ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 44     | 2      | 10     | 84     | 1      | 41   |      |
| ψ <sub>JB</sub>               | Junction-to-board characterization parameter | 62     | 64     | 77     | 271    | 50     | 294  |      |
| R <sub>θJC(bot)</sub>         | Junction-to-case (bottom) thermal resistance | -      | -      | -      | -      | -      | 250  |      |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER         | TEST CONDITIONS  | V <sub>CC</sub> | - 40°C TO 85°C     |     | - 40°C TO 125°C RECOMMENDED |     | UNIT |
|-------------------|--|-----------------|--------------------|-----|-----------------------------|-----|------|
|                   |  |                 | TYP <sup>(1)</sup> | MAX | TYP                         | MAX |      |
| V <sub>OL</sub>   | I <sub>OL</sub> = 100 μA   | 1.65 V to 5.5 V | 0.1                |     | 0.1                         |     | V    |
|                   | I <sub>OL</sub> = 4 mA   | 1.65 V          | 0.45               |     | 0.45                        |     |      |
|                   | I <sub>OL</sub> = 8 mA   | 2.3 V           | 0.3                |     | 0.3                         |     |      |
|                   | I <sub>OL</sub> = 16 mA  | 3 V             | 0.4                |     | 0.4                         |     |      |
|                   | I <sub>OL</sub> = 24 mA  |                 | 0.55               |     | 0.55                        |     |      |
|                   | I <sub>OL</sub> = 32 mA  | 4.5 V           | 0.55               |     | 0.55                        |     |      |
| I <sub>I</sub>    | A input<br>V <sub>I</sub> = 5.5 V or GND                                     | 0 to 5.5 V      | ±5                 |     | ±5                          |     | μA   |
| I <sub>off</sub>  | V <sub>I</sub> or V <sub>O</sub> = 5.5 V                                     | 0               | ±10                |     | ±10                         |     | μA   |
| I <sub>CC</sub>   | V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0                            | 1.65 V to 5.5 V | 10                 |     | 10                          |     | μA   |
| Δ I <sub>CC</sub> | One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND | 3 V to 5.5 V    | 500                |     | 500                         |     | μA   |
| C <sub>i</sub>    | V <sub>I</sub> = V <sub>CC</sub> or GND                                      | 3.3 V           | 4                  |     | 4                           |     | pF   |
| C <sub>o</sub>    | V <sub>O</sub> = V <sub>CC</sub> or GND                                      | 3.3 V           | 5                  |     | 5                           |     | pF   |

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## 6.6 Switching Characteristics, - 40°C to 85°C

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 7-1](#))

| PARAMETER       | FROM (INPUT) | TO (OUTPUT) | - 40°C TO 85°C                   |     |                                 |     |                                 |     |                               |     | UNIT |
|-----------------|--------------|-------------|----------------------------------|-----|---------------------------------|-----|---------------------------------|-----|-------------------------------|-----|------|
|                 |              |             | V <sub>CC</sub> = 1.8 V ± 0.15 V |     | V <sub>CC</sub> = 2.5 V ± 0.2 V |     | V <sub>CC</sub> = 3.3 V ± 0.3 V |     | V <sub>CC</sub> = 5 V ± 0.5 V |     |      |
|                 |              |             | MIN                              | MAX | MIN                             | MAX | MIN                             | MAX | MIN                           | MAX |      |
| t <sub>pd</sub> | A            | Y           | 2.4                              | 8.3 | 1                               | 5.5 | 1.5                             | 4.2 | 1                             | 3.5 | ns   |

## 6.7 Switching Characteristics, - 40°C to 125°C

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 7-1](#))

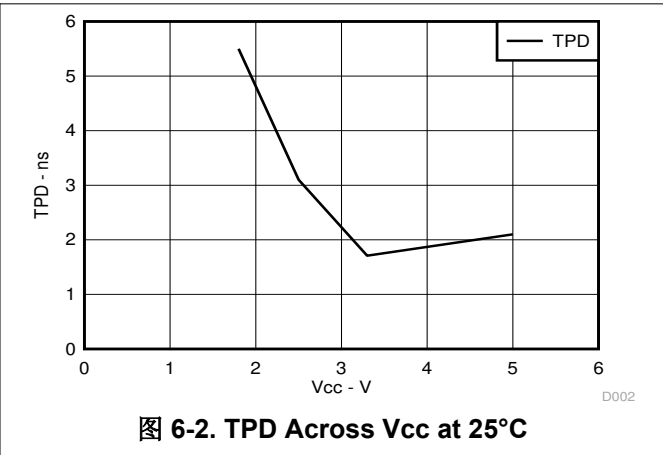
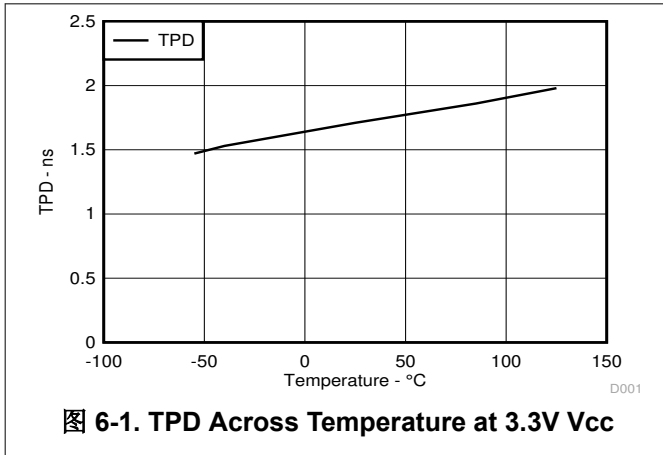
| PARAMETER       | FROM (INPUT) | TO (OUTPUT) | - 40°C TO 125°C RECOMMENDED      |     |                                 |     |                                 |     |                               |     | UNIT |
|-----------------|--------------|-------------|----------------------------------|-----|---------------------------------|-----|---------------------------------|-----|-------------------------------|-----|------|
|                 |              |             | V <sub>CC</sub> = 1.8 V ± 0.15 V |     | V <sub>CC</sub> = 2.5 V ± 0.2 V |     | V <sub>CC</sub> = 3.3 V ± 0.3 V |     | V <sub>CC</sub> = 5 V ± 0.5 V |     |      |
|                 |              |             | MIN                              | MAX | MIN                             | MAX | MIN                             | MAX | MIN                           | MAX |      |
| t <sub>pd</sub> | A            | Y           | 2.4                              | 8.6 | 1                               | 6   | 1.5                             | 4.7 | 1                             | 4   | ns   |

## 6.8 Operating Characteristics

T<sub>A</sub> = 25°C

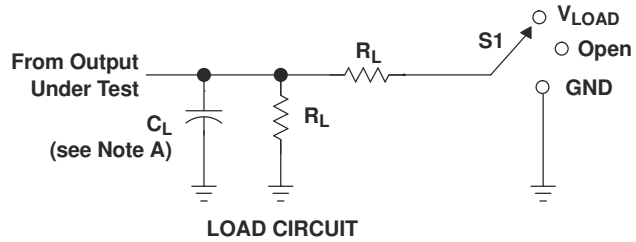
| PARAMETER       | TEST CONDITIONS                             | V <sub>CC</sub> = 1.8 V | V <sub>CC</sub> = 2.5 V | V <sub>CC</sub> = 3.3 V | V <sub>CC</sub> = 5 V | UNIT |
|-----------------|---|-------------------------|-------------------------|-------------------------|-----------------------|------|
|                 |   | TYP                     | TYP                     | TYP                     | TYP                   |      |
| C <sub>pd</sub> | Power dissipation capacitance<br>f = 10 MHz | 3                       | 3                       | 4                       | 6                     | pF   |

### 6.9 Typical Characteristics



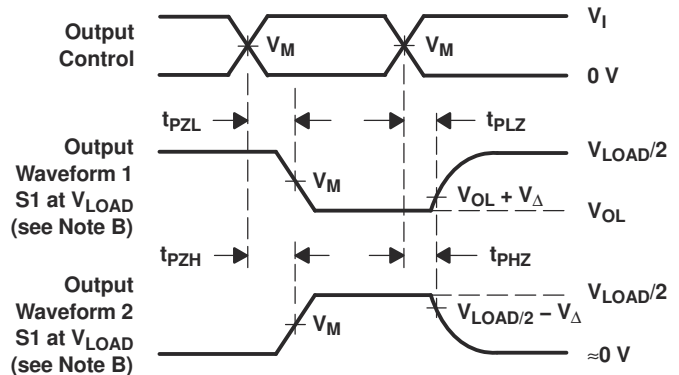
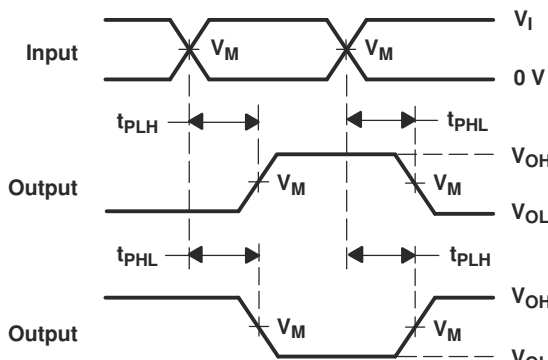
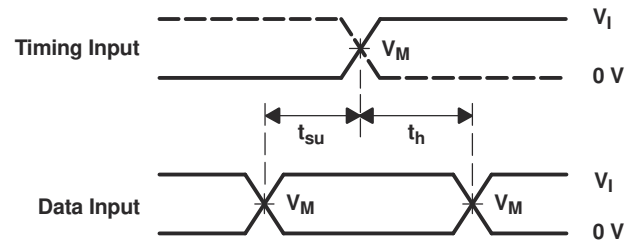
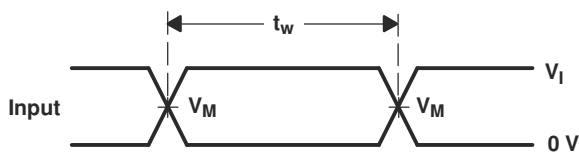
## 7 Parameter Measurement Information

### 7.1 (Open Drain)



| TEST                          | S1         |
|-------------------------------|------------|
| $t_{pZL}$ (see Notes E and F) | $V_{LOAD}$ |
| $t_{pLZ}$ (see Notes E and G) | $V_{LOAD}$ |
| $t_{PHZ}/t_{PZH}$             | $V_{LOAD}$ |

| $V_{CC}$                         | INPUT    |                      | $V_M$      | $V_{LOAD}$        | $C_L$ | $R_L$        | $V_{\Delta}$ |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
|                                  | $V_I$    | $t_r/t_f$            |            |                   |       |              |              |
| $1.8\text{ V} \pm 0.15\text{ V}$ | $V_{CC}$ | $\leq 2\text{ ns}$   | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k $\Omega$ | 0.15 V       |
| $2.5\text{ V} \pm 0.2\text{ V}$  | $V_{CC}$ | $\leq 2\text{ ns}$   | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 $\Omega$ | 0.15 V       |
| $3.3\text{ V} \pm 0.3\text{ V}$  | 3 V      | $\leq 2.5\text{ ns}$ | 1.5 V      | 6 V               | 50 pF | 500 $\Omega$ | 0.3 V        |
| $5\text{ V} \pm 0.5\text{ V}$    | $V_{CC}$ | $\leq 2.5\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 50 pF | 500 $\Omega$ | 0.3 V        |



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E. Since this device has open-drain outputs,  $t_{pLZ}$  and  $t_{pZL}$  are the same as  $t_{pd}$ .  
 F.  $t_{pZL}$  is measured at  $V_M$ .  
 G.  $t_{pLZ}$  is measured at  $V_{OL} + V_{\Delta}$ .  
 H. All parameters and waveforms are not applicable to all devices.

图 7-1. Load Circuit and Voltage Waveforms

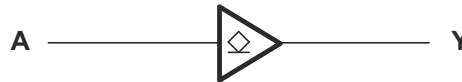
## 8 Detailed Description

### 8.1 Overview

The SN74LVC1G07 device contains one open-drain buffer with a maximum sink current of 32 mA. This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The DPW package technology is a major breakthrough in IC packaging. The DPW 0.64 mm square footprint saves significant board space over other package options while still retaining the traditional manufacturing friendly lead pitch of 0.5 mm.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

- Wide operating voltage range.
  - Operates from 1.65 V to 5.5 V.
- Allows down voltage translation.
- Inputs and outputs accept voltages to 5.5 V.
- $I_{off}$  feature allows voltages on the inputs and outputs, when  $V_{CC}$  is 0 V.

### 8.4 Device Functional Modes

Function Table

| INPUT<br>A | OUTPUT<br>Y |
|------------|-------------|
| L          | L           |
| H          | Z           |

## 9 Application and Implementation

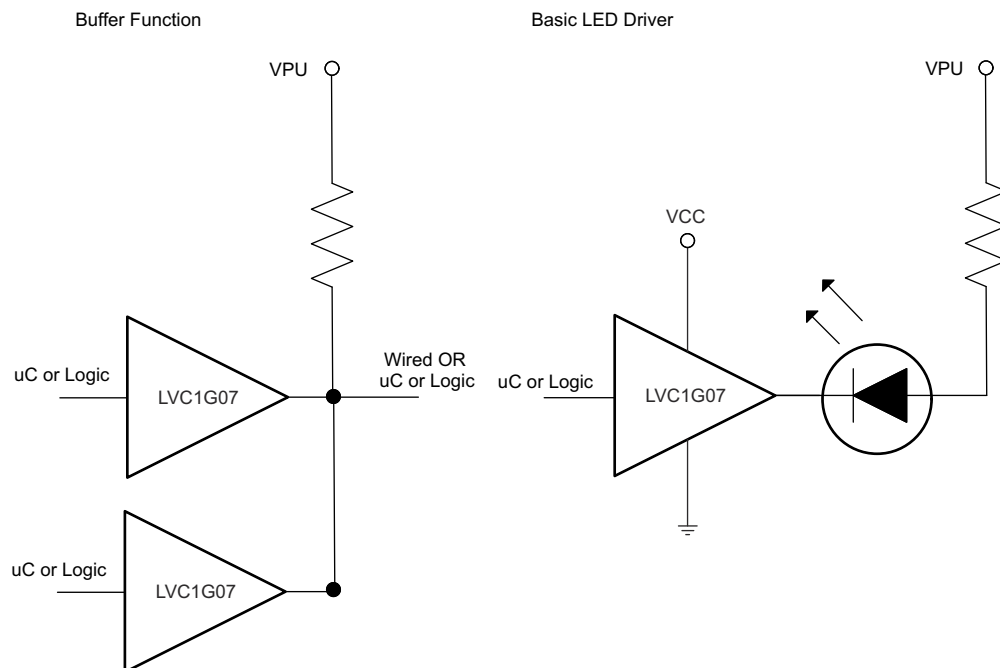
### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The SN74LVC1G07 is a high drive CMOS device that can be used to implement a high output drive buffer, such as an LED application. It can sink 32 mA of current at 4.5 V making it ideal for high drive and wired-OR/AND functions. It is good for high speed applications up to 100 MHz. The inputs are 5.5 V tolerant allowing it to translate up/down to  $V_{CC}$ .

### 9.2 Typical Application



#### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it may drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

#### 9.2.2 Detailed Design Procedure

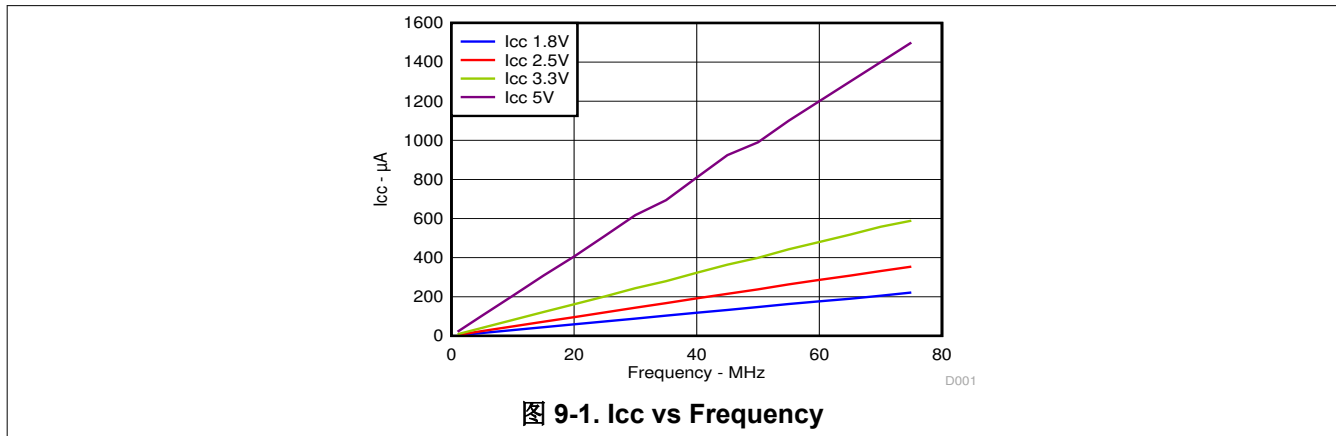
##### 1. Recommended Input Conditions

- Rise time and fall time specs. See ( $\Delta t / \Delta V$ ) in the [Recommended Operating Conditions](#) table.
- Specified high and low levels. See ( $V_{IH}$  and  $V_{IL}$ ) in the [Recommended Operating Conditions](#) table.
- Inputs are over-voltage tolerant allowing them to go as high as ( $V_I$  max) in the [Recommended Operating Conditions](#) table at any valid  $V_{CC}$ .

##### 2. Recommend Output Conditions

- Load currents should not exceed ( $I_O$  max) per output and should not exceed (Continuous current through  $V_{CC}$  or GND) total current for the part. These limits are located in the [Absolute Maximum Ratings](#) table.
- Outputs should not be pulled above 5.5 V.

### 9.2.3 Application Curves



## 10 Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in the [Recommended Operating Conditions](#) table.

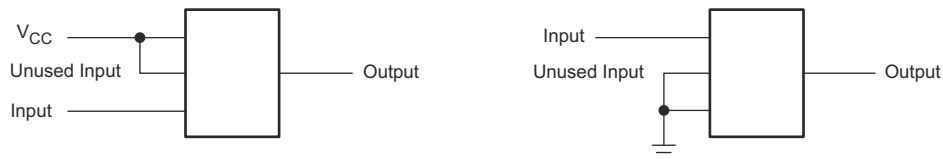
Each V<sub>cc</sub> pin should have a good bypass capacitor to prevent power disturbance. A 0.1-µF capacitor is recommended for devices with a single supply. If there are multiple V<sub>cc</sub> pins then a 0.01-µF or 0.022-µF capacitor is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. 0.1-µF and 1-µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally, they will be tied to Gnd or V<sub>cc</sub>, whichever is more convenient.

### 11.2 Layout Example



## 12 Device and Documentation Support

### 12.1 Trademarks

所有商标均为其各自所有者的财产。

### 12.2 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.3 Glossary

**TI Glossary** This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

| Orderable Device  | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2)     | Lead finish/<br>Ball material<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5)   | Samples                 |
|-------------------|---------------|--------------|-----------------|------|-------------|---------------------|--------------------------------------|----------------------|--------------|---|-------------------------|
| SN74LVC1G07DBVR   | ACTIVE        | SOT-23       | DBV             | 5    | 3000        | RoHS & Green        | NIPDAU   SN                          | Level-1-260C-UNLIM   | -40 to 125   | (C075, C07F, C07J,<br>C07K, C07R, C<br>07T)<br>(C07H, C07P, C07S) | <a href="#">Samples</a> |
| SN74LVC1G07DBVRE4 | ACTIVE        | SOT-23       | DBV             | 5    | 3000        | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | C07F  | <a href="#">Samples</a> |
| SN74LVC1G07DBVRG4 | ACTIVE        | SOT-23       | DBV             | 5    | 3000        | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | C07F  | <a href="#">Samples</a> |
| SN74LVC1G07DBVT   | ACTIVE        | SOT-23       | DBV             | 5    | 250         | RoHS & Green        | NIPDAU   SN                          | Level-1-260C-UNLIM   | -40 to 125   | (C075, C07F, C07J,<br>C07K, C07R)<br>(C07H, C07P, C07S)           | <a href="#">Samples</a> |
| SN74LVC1G07DBVTE4 | ACTIVE        | SOT-23       | DBV             | 5    | 250         | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | C07F  | <a href="#">Samples</a> |
| SN74LVC1G07DBVTG4 | ACTIVE        | SOT-23       | DBV             | 5    | 250         | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | C07F  | <a href="#">Samples</a> |
| SN74LVC1G07DCK3   | ACTIVE        | SC70         | DCK             | 5    | 3000        | RoHS &<br>Non-Green | SNBI                                 | Level-1-260C-UNLIM   | -40 to 125   | (CVF, CVZ)  | <a href="#">Samples</a> |
| SN74LVC1G07DCKR   | ACTIVE        | SC70         | DCK             | 5    | 3000        | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | (CV5, CVF, CVK, CV<br>R, CVT)<br>(CVH, CVP, CVS)                  | <a href="#">Samples</a> |
| SN74LVC1G07DCKRE4 | ACTIVE        | SC70         | DCK             | 5    | 3000        | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | (CV5, CVF, CVK, CV<br>R, CVT)<br>(CVH, CVP, CVS)                  | <a href="#">Samples</a> |
| SN74LVC1G07DCKRG4 | ACTIVE        | SC70         | DCK             | 5    | 3000        | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | (CV5, CVF, CVK, CV<br>R, CVT)<br>(CVH, CVP, CVS)                  | <a href="#">Samples</a> |
| SN74LVC1G07DCKT   | ACTIVE        | SC70         | DCK             | 5    | 250         | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | (CV5, CVF, CVK, CV<br>R, CVT)<br>CVH                              | <a href="#">Samples</a> |
| SN74LVC1G07DCKTE4 | ACTIVE        | SC70         | DCK             | 5    | 250         | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | (CV5, CVF, CVK, CV<br>R, CVT)<br>CVH                              | <a href="#">Samples</a> |
| SN74LVC1G07DCKTG4 | ACTIVE        | SC70         | DCK             | 5    | 250         | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | (CV5, CVF, CVK, CV<br>R, CVT)                                     | <a href="#">Samples</a> |

| Orderable Device  | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2) | Lead finish/<br>Ball material<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|-------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
|                   |               |              |                 |      |             |                 |                                      |                      |              | CVH                     |                         |
| SN74LVC1G07DPWR   | ACTIVE        | X2SON        | DPW             | 5    | 3000        | RoHS & Green    | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | L4                      | <a href="#">Samples</a> |
| SN74LVC1G07DRLR   | ACTIVE        | SOT-5X3      | DRL             | 5    | 4000        | RoHS & Green    | NIPDAU   NIPDAUAG                    | Level-1-260C-UNLIM   | -40 to 125   | (CV7, CVR)              | <a href="#">Samples</a> |
| SN74LVC1G07DRLRG4 | ACTIVE        | SOT-5X3      | DRL             | 5    | 4000        | RoHS & Green    | NIPDAUAG                             | Level-1-260C-UNLIM   | -40 to 125   | (CV7, CVR)              | <a href="#">Samples</a> |
| SN74LVC1G07DRY2   | ACTIVE        | SON          | DRY             | 6    | 5000        | RoHS & Green    | NIPDAU   NIPDAUAG                    | Level-1-260C-UNLIM   | -40 to 125   | CV                      | <a href="#">Samples</a> |
| SN74LVC1G07DRYR   | ACTIVE        | SON          | DRY             | 6    | 5000        | RoHS & Green    | Call TI   NIPDAUAG<br>  NIPDAU       | Level-1-260C-UNLIM   | -40 to 125   | CV                      | <a href="#">Samples</a> |
| SN74LVC1G07DRYRG4 | ACTIVE        | SON          | DRY             | 6    | 5000        | RoHS & Green    | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 125   | CV                      | <a href="#">Samples</a> |
| SN74LVC1G07DSF2   | ACTIVE        | SON          | DSF             | 6    | 5000        | RoHS & Green    | NIPDAU   NIPDAUAG                    | Level-1-260C-UNLIM   | -40 to 125   | CV                      | <a href="#">Samples</a> |
| SN74LVC1G07DSFR   | ACTIVE        | SON          | DSF             | 6    | 5000        | RoHS & Green    | NIPDAU   NIPDAUAG                    | Level-1-260C-UNLIM   | -40 to 125   | CV                      | <a href="#">Samples</a> |
| SN74LVC1G07YZPR   | ACTIVE        | DSBGA        | YZP             | 5    | 3000        | RoHS & Green    | SNAGCU                               | Level-1-260C-UNLIM   | -40 to 85    | (CV7, CVN)              | <a href="#">Samples</a> |
| SN74LVC1G07YZVR   | ACTIVE        | DSBGA        | YZV             | 4    | 3000        | RoHS & Green    | SNAGCU                               | Level-1-260C-UNLIM   | -40 to 85    | CV<br>N                 | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LVC1G07 :**

- Automotive : [SN74LVC1G07-Q1](#)
- Enhanced Product : [SN74LVC1G07-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

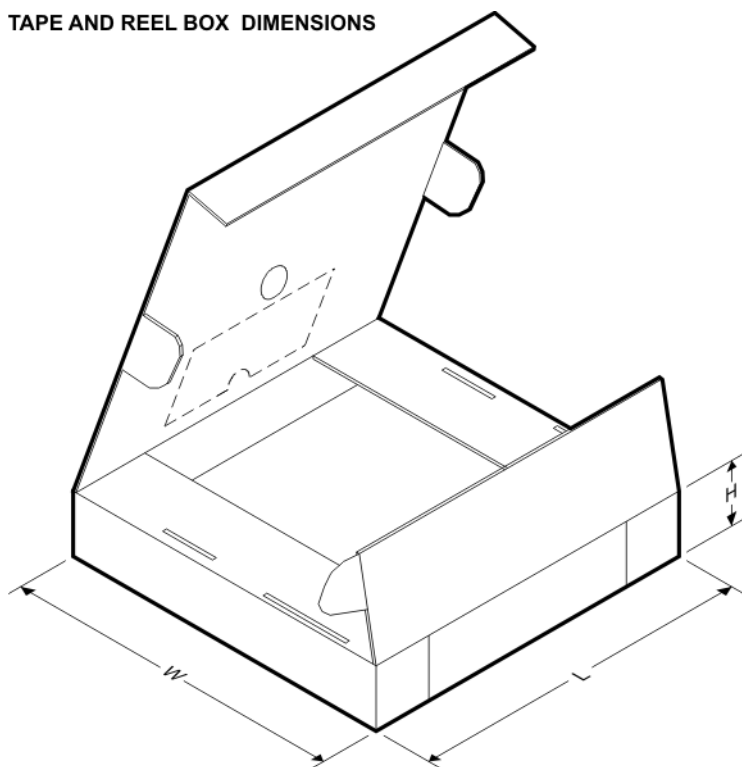
**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

| Device            | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC1G07DBVR   | SOT-23       | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.3     | 3.2     | 1.4     | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVR   | SOT-23       | DBV             | 5    | 3000 | 178.0              | 9.2                | 3.3     | 3.23    | 1.55    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVR   | SOT-23       | DBV             | 5    | 3000 | 180.0              | 8.4                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVRG4 | SOT-23       | DBV             | 5    | 3000 | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 180.0              | 8.4                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 178.0              | 9.2                | 3.3     | 3.23    | 1.55    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 178.0              | 9.0                | 3.3     | 3.2     | 1.4     | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DBVTG4 | SOT-23       | DBV             | 5    | 250  | 178.0              | 9.0                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DCKR   | SC70         | DCK             | 5    | 3000 | 180.0              | 8.4                | 2.47    | 2.3     | 1.25    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DCKR   | SC70         | DCK             | 5    | 3000 | 178.0              | 9.2                | 2.4     | 2.4     | 1.22    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DCKT   | SC70         | DCK             | 5    | 250  | 180.0              | 8.4                | 2.47    | 2.3     | 1.25    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DCKT   | SC70         | DCK             | 5    | 250  | 178.0              | 9.0                | 2.4     | 2.5     | 1.2     | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DCKT   | SC70         | DCK             | 5    | 250  | 178.0              | 9.2                | 2.4     | 2.4     | 1.22    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DPWR   | X2SON        | DPW             | 5    | 3000 | 178.0              | 8.4                | 0.91    | 0.91    | 0.5     | 2.0     | 8.0    | Q3            |
| SN74LVC1G07DRLR   | SOT-5X3      | DRL             | 5    | 4000 | 180.0              | 8.4                | 1.98    | 1.78    | 0.69    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DRY2   | SON          | DRY             | 6    | 5000 | 180.0              | 9.5                | 1.6     | 1.15    | 0.75    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DRY2   | SON          | DRY             | 6    | 5000 | 180.0              | 8.4                | 1.65    | 1.2     | 0.7     | 4.0     | 8.0    | Q3            |

| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC1G07DSF2 | SON          | DSF             | 6    | 5000 | 180.0              | 9.5                | 1.16    | 1.16    | 0.5     | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DSF2 | SON          | DSF             | 6    | 5000 | 180.0              | 8.4                | 1.16    | 1.16    | 0.63    | 4.0     | 8.0    | Q3            |
| SN74LVC1G07DSFR | SON          | DSF             | 6    | 5000 | 180.0              | 8.4                | 1.16    | 1.16    | 0.63    | 4.0     | 8.0    | Q2            |
| SN74LVC1G07DSFR | SON          | DSF             | 6    | 5000 | 180.0              | 9.5                | 1.16    | 1.16    | 0.5     | 4.0     | 8.0    | Q2            |
| SN74LVC1G07YZPR | DSBGA        | YZP             | 5    | 3000 | 178.0              | 9.2                | 1.02    | 1.52    | 0.63    | 4.0     | 8.0    | Q1            |
| SN74LVC1G07YZVR | DSBGA        | YZV             | 4    | 3000 | 178.0              | 9.2                | 1.0     | 1.0     | 0.63    | 4.0     | 8.0    | Q1            |

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

| Device            | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC1G07DBVR   | SOT-23       | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DBVR   | SOT-23       | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DBVR   | SOT-23       | DBV             | 5    | 3000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DBVRG4 | SOT-23       | DBV             | 5    | 3000 | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DBVT   | SOT-23       | DBV             | 5    | 250  | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DBVTG4 | SOT-23       | DBV             | 5    | 250  | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DCKR   | SC70         | DCK             | 5    | 3000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DCKR   | SC70         | DCK             | 5    | 3000 | 180.0       | 180.0      | 18.0        |

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC1G07DCKT | SC70         | DCK             | 5    | 250  | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DCKT | SC70         | DCK             | 5    | 250  | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DCKT | SC70         | DCK             | 5    | 250  | 180.0       | 180.0      | 18.0        |
| SN74LVC1G07DPWR | X2SON        | DPW             | 5    | 3000 | 205.0       | 200.0      | 33.0        |
| SN74LVC1G07DRLR | SOT-5X3      | DRL             | 5    | 4000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DRY2 | SON          | DRY             | 6    | 5000 | 184.0       | 184.0      | 19.0        |
| SN74LVC1G07DRY2 | SON          | DRY             | 6    | 5000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DSF2 | SON          | DSF             | 6    | 5000 | 184.0       | 184.0      | 19.0        |
| SN74LVC1G07DSF2 | SON          | DSF             | 6    | 5000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DSFR | SON          | DSF             | 6    | 5000 | 202.0       | 201.0      | 28.0        |
| SN74LVC1G07DSFR | SON          | DSF             | 6    | 5000 | 184.0       | 184.0      | 19.0        |
| SN74LVC1G07YZPR | DSBGA        | YZP             | 5    | 3000 | 220.0       | 220.0      | 35.0        |
| SN74LVC1G07YZVR | DSBGA        | YZV             | 4    | 3000 | 220.0       | 220.0      | 35.0        |

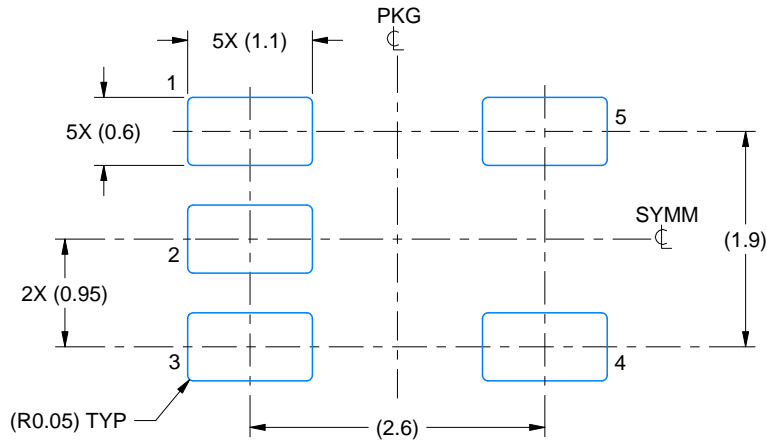


# EXAMPLE BOARD LAYOUT

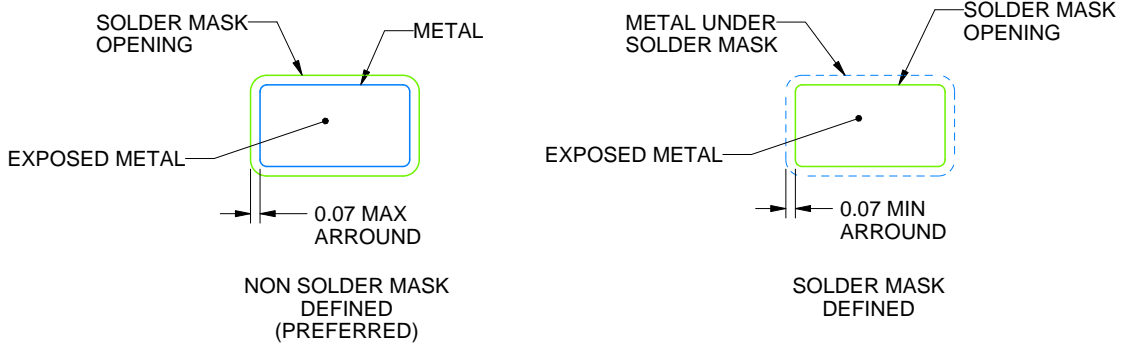
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214839/F 06/2021

NOTES: (continued)

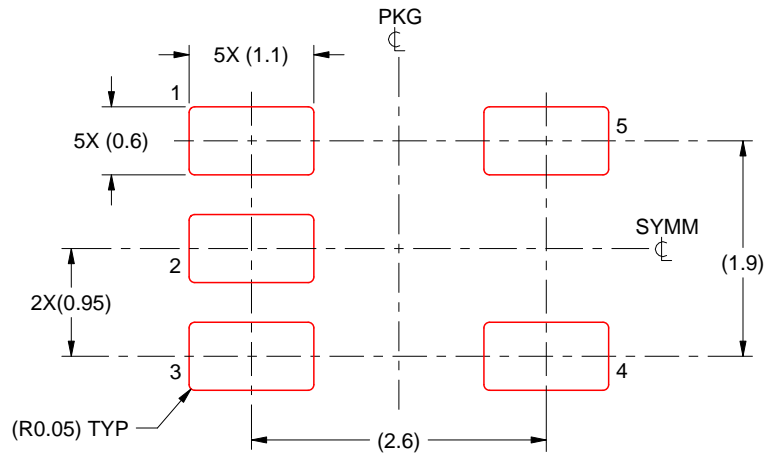
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/F 06/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

DPW 5

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4211218-3/D



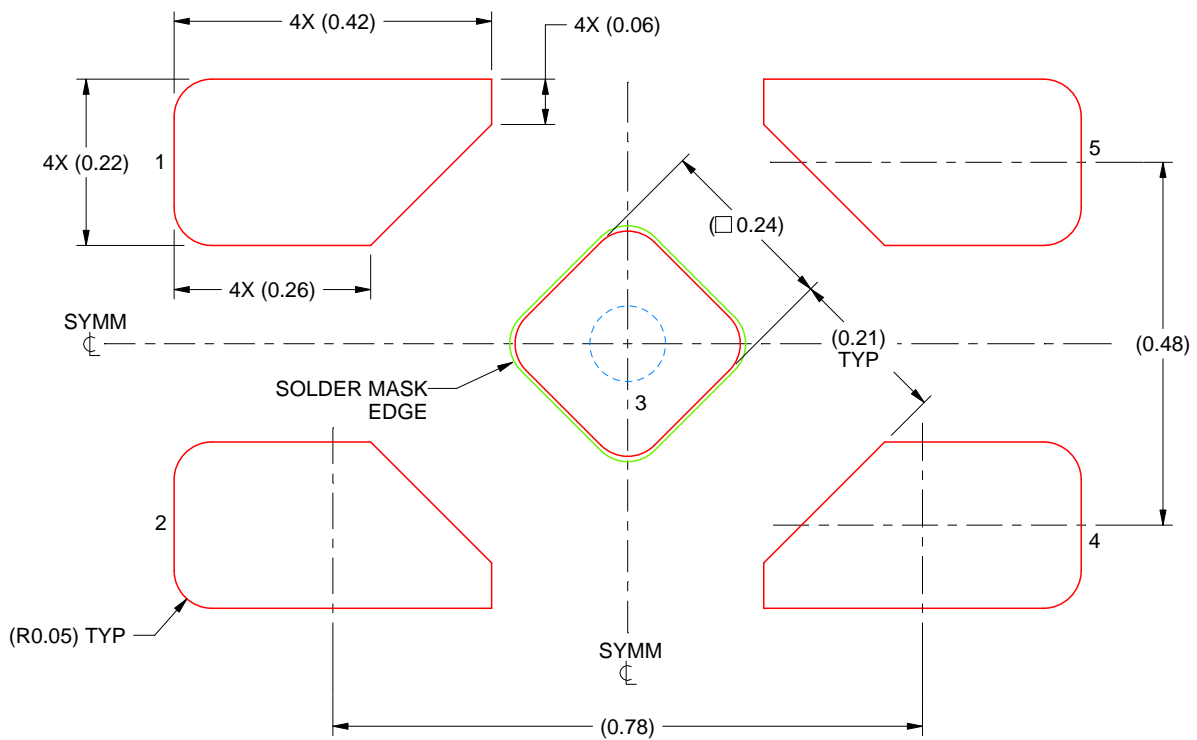


# EXAMPLE STENCIL DESIGN

DPW0005A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 3  
92% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:100X

4223102/D 03/2022

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



# EXAMPLE BOARD LAYOUT

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



SOLDER MASK DETAILS  
NOT TO SCALE

4219492/A 05/2017

NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:40X

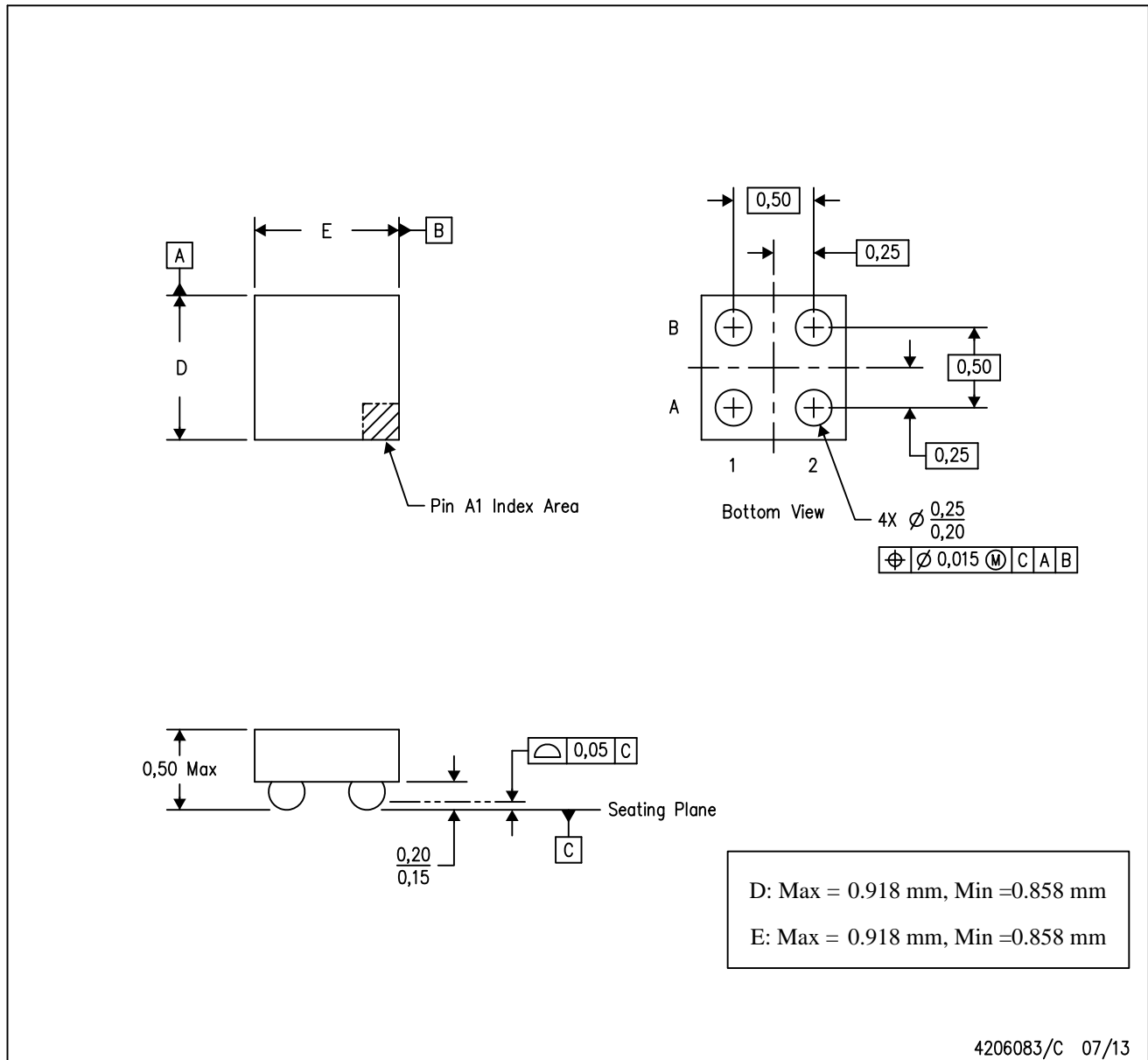
4219492/A 05/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

YZV (S-XBGA-N4)

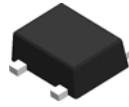
DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments.

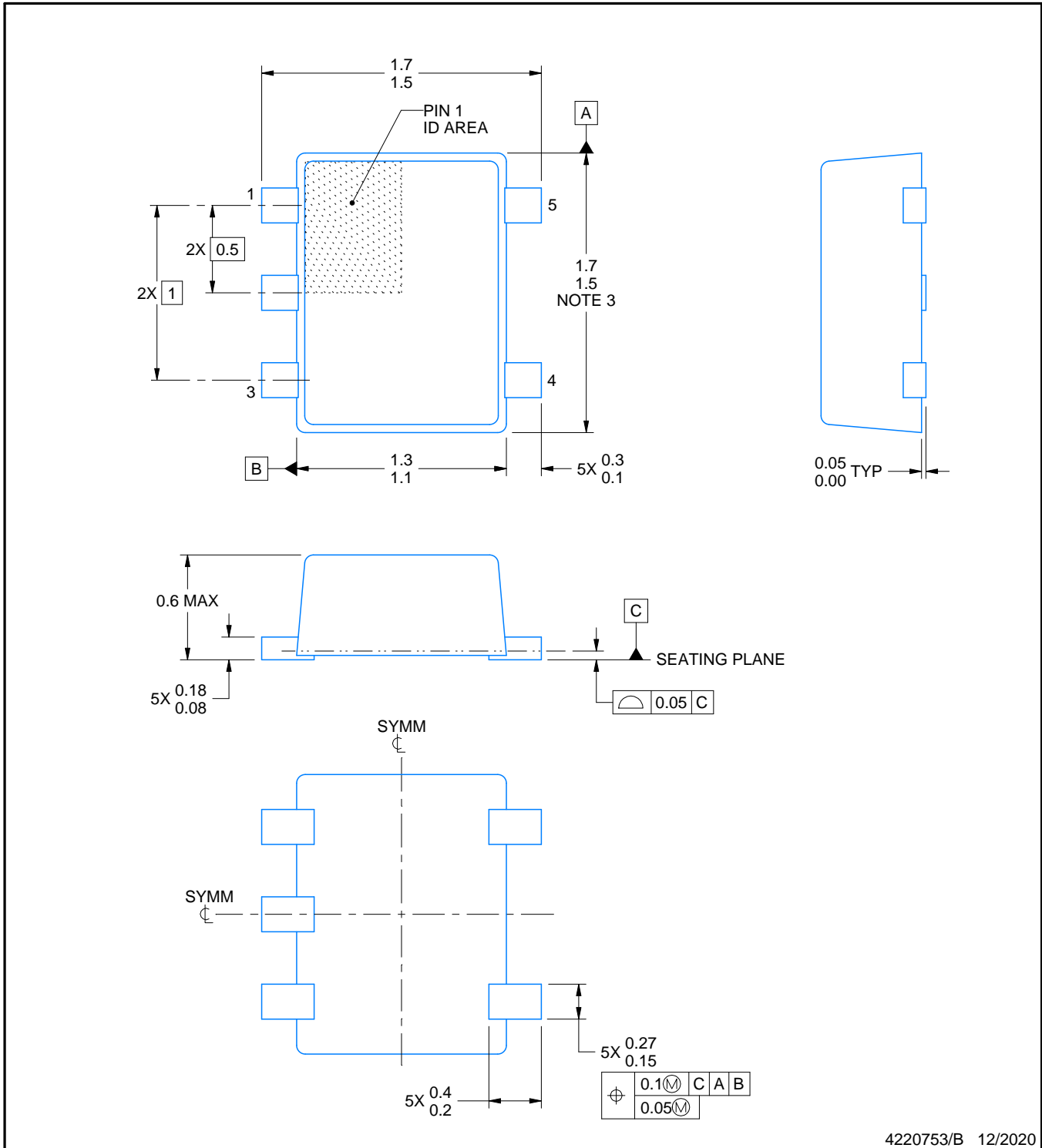
DRL0005A



# PACKAGE OUTLINE

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



4220753/B 12/2020

NOTES:

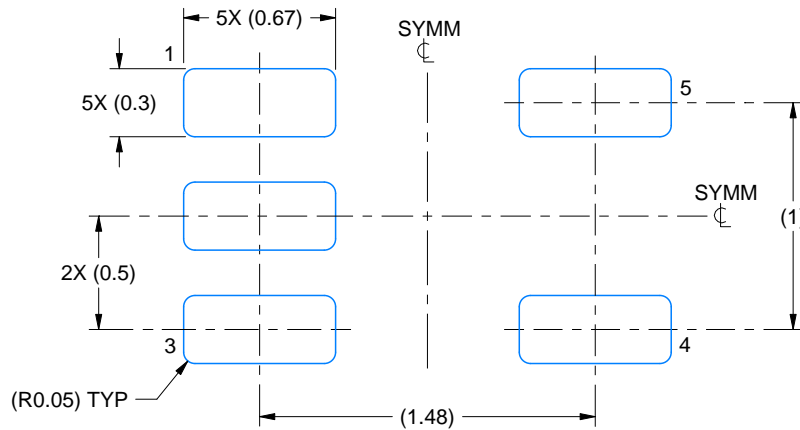
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

# EXAMPLE BOARD LAYOUT

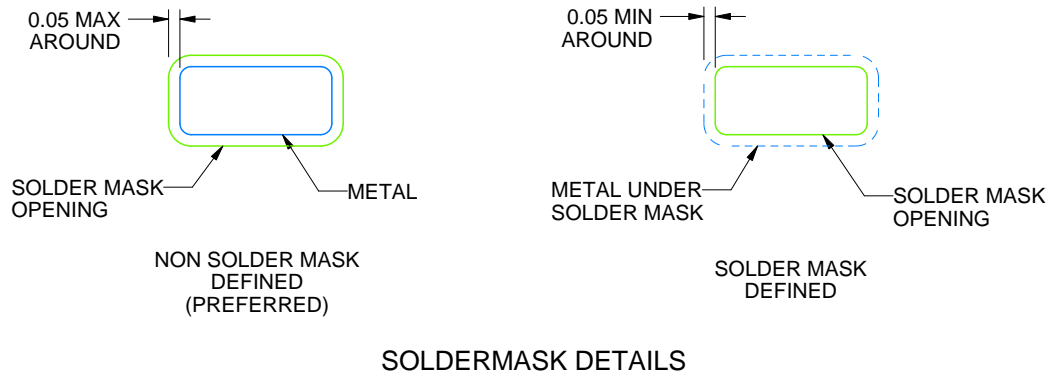
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDERMASK DETAILS

4220753/B 12/2020

NOTES: (continued)

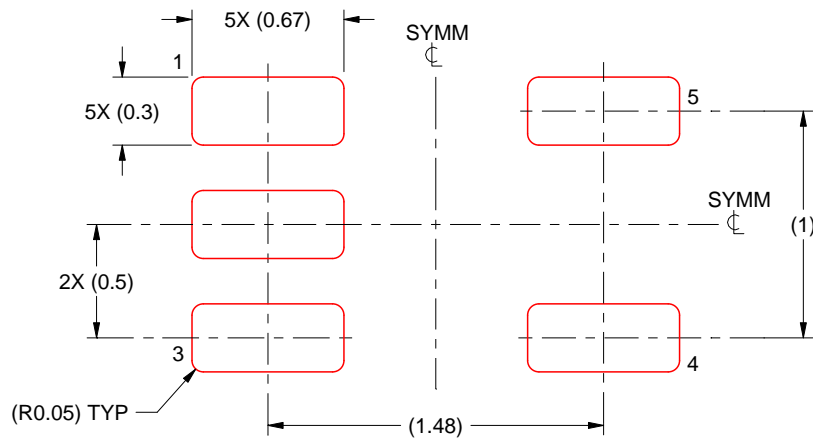
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE

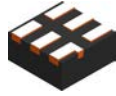


SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X

4220753/B 12/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

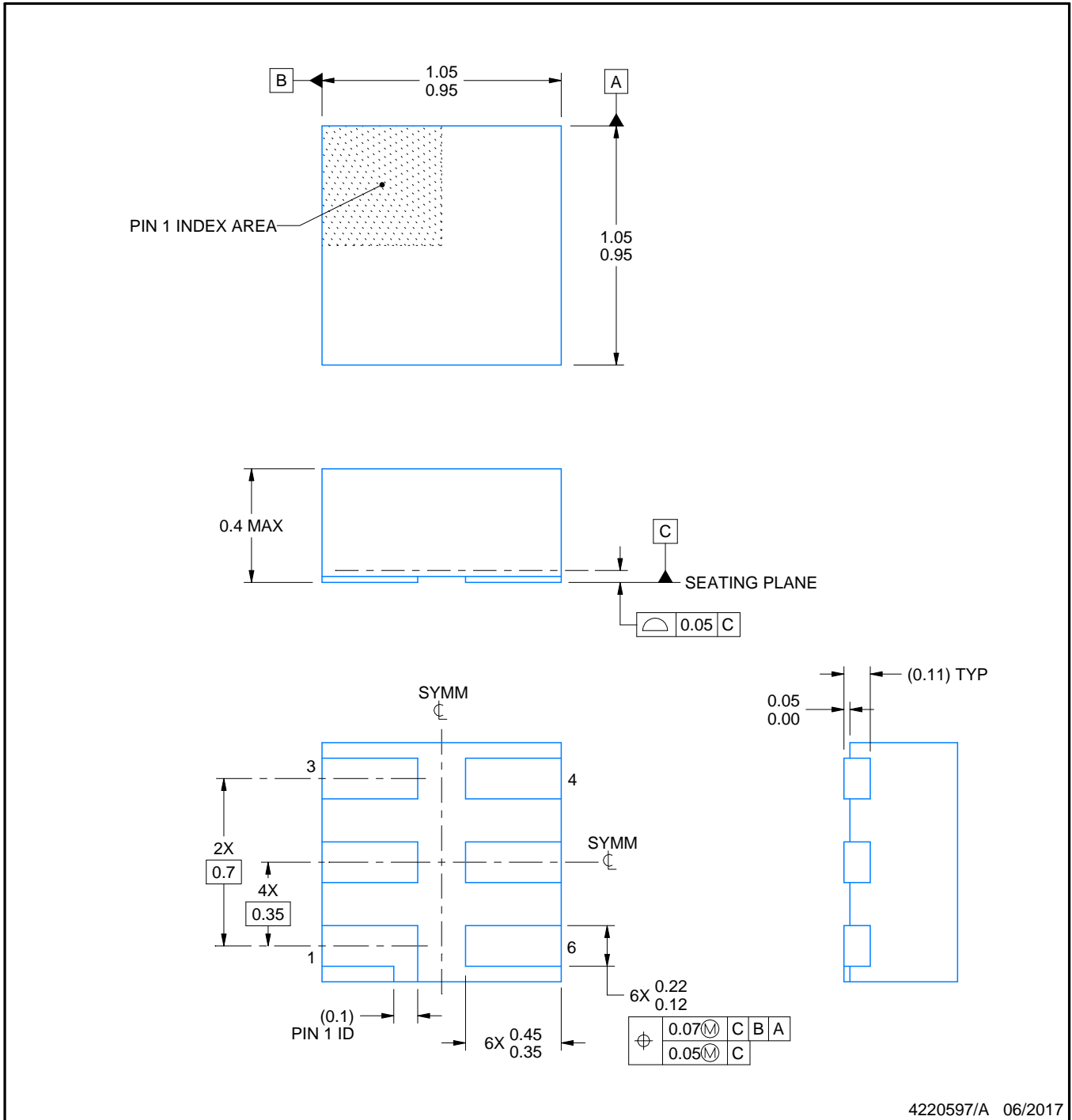


# DSF0006A

# PACKAGE OUTLINE

## X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4220597/A 06/2017

### NOTES:

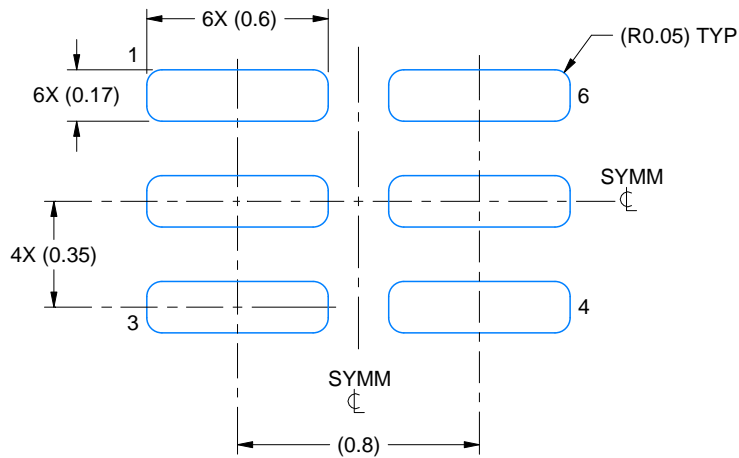
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

# EXAMPLE BOARD LAYOUT

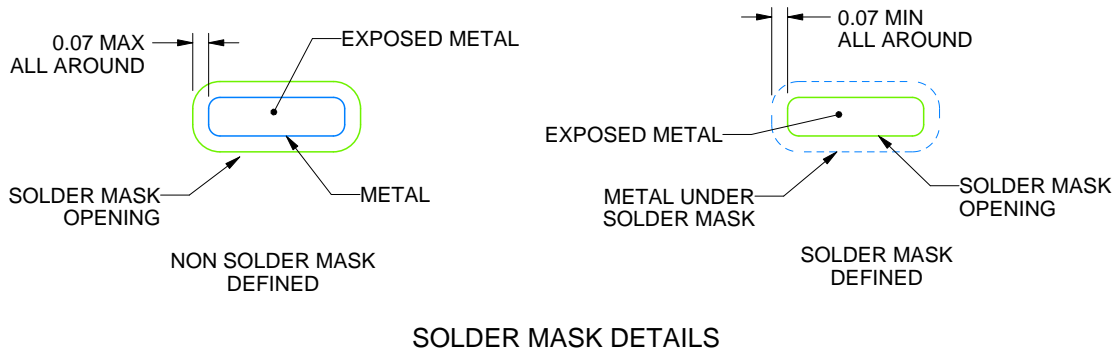
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4220597/A 06/2017

NOTES: (continued)

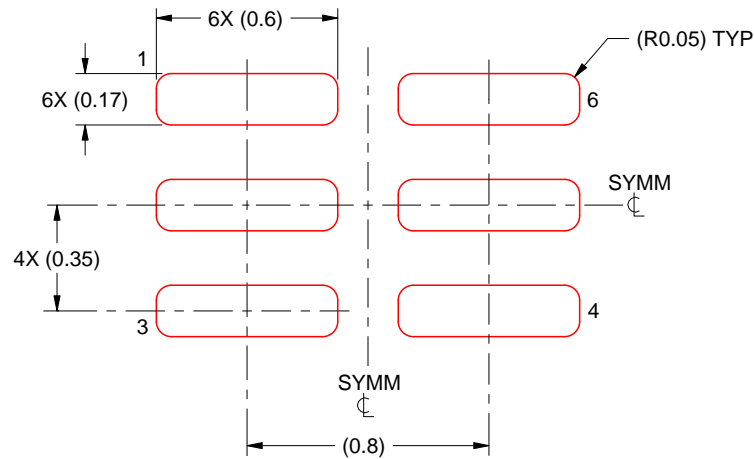
4. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



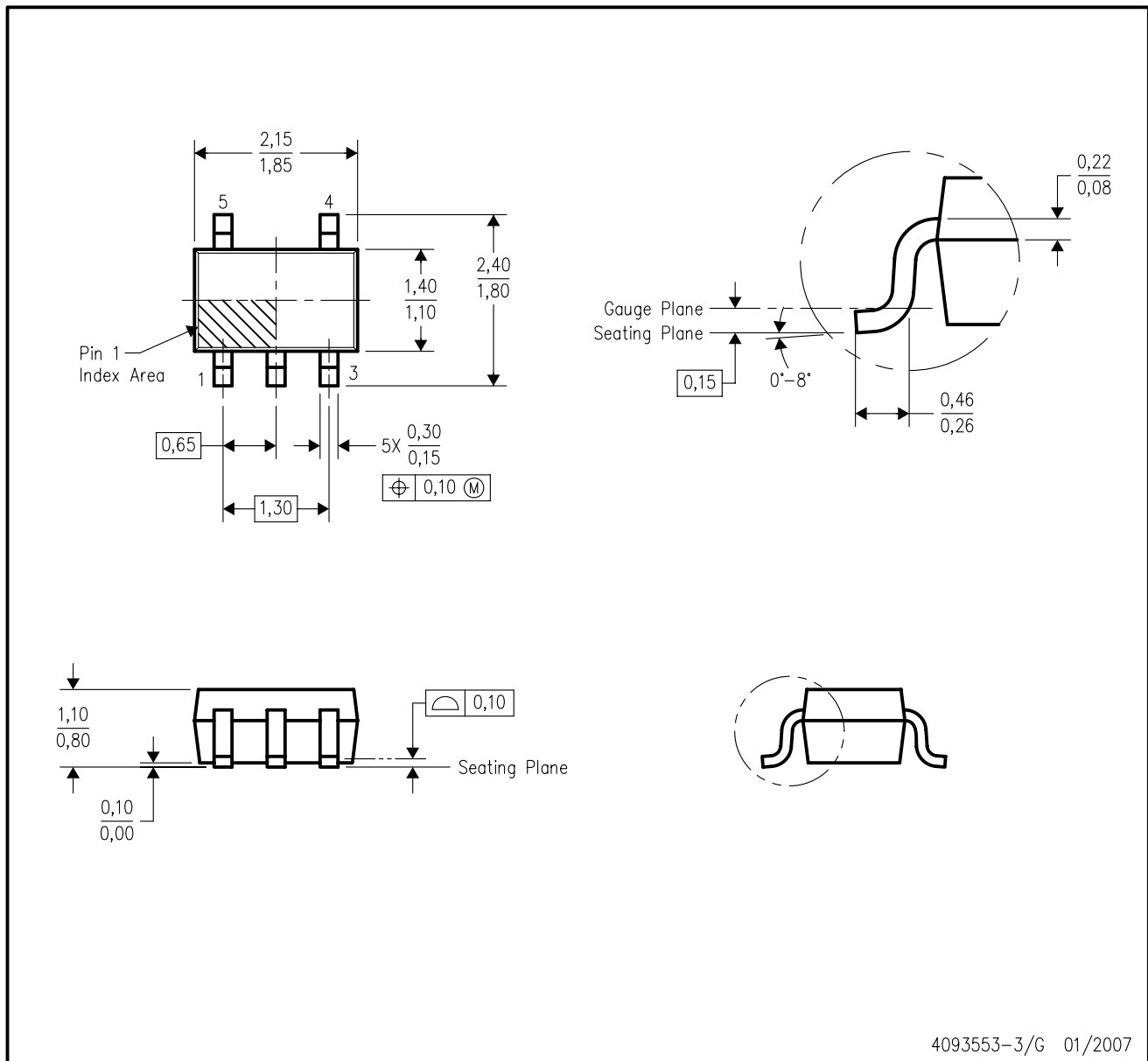
SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:40X

4220597/A 06/2017

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

DCK (R-PDSO-G5)

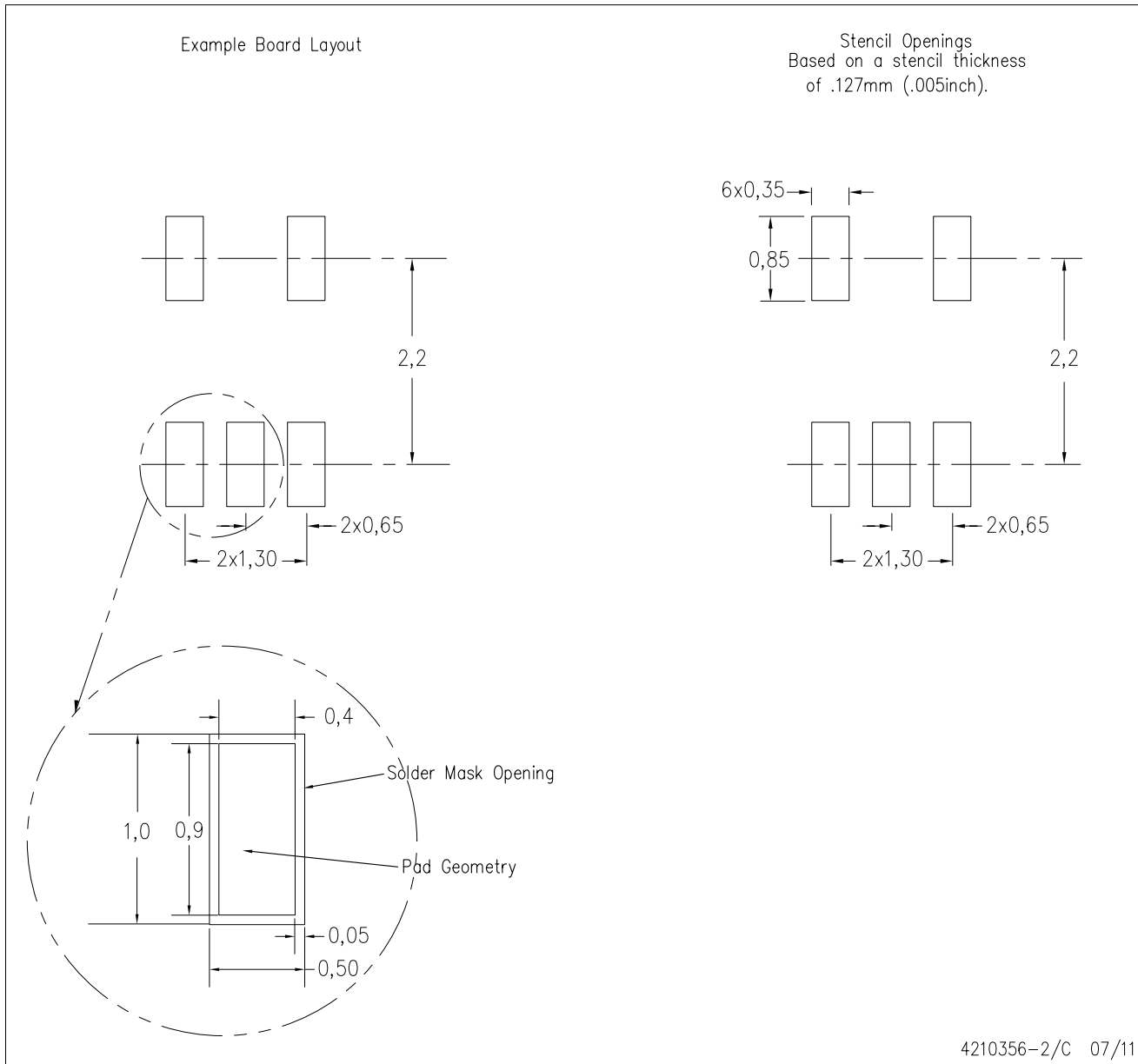
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

## GENERIC PACKAGE VIEW

**DRY 6**

**USON - 0.6 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4207181/G

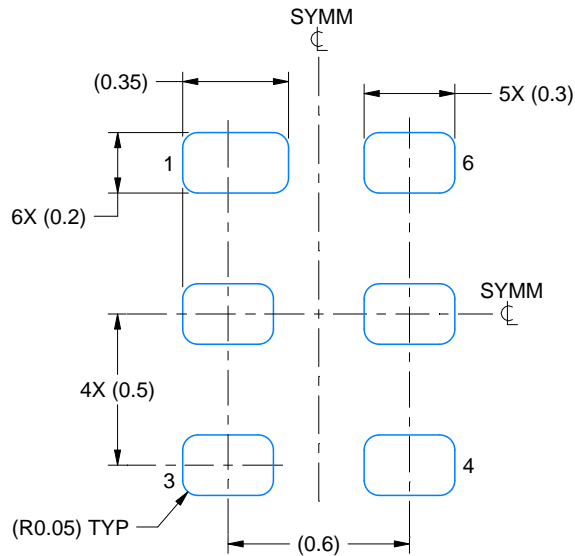


# EXAMPLE BOARD LAYOUT

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



**LAND PATTERN EXAMPLE**  
1:1 RATIO WITH PKG SOLDER PADS  
EXPOSED METAL SHOWN  
SCALE:40X



**SOLDER MASK DETAILS**

4222894/A 01/2018

NOTES: (continued)

3. For more information, see QFN/SON PCB application report in literature No. SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).

# EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.075 - 0.1 mm THICK STENCIL  
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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